

## CLAIMS

What is claimed is:

- 1 1. A method of fabricating an electronic package, the method comprising:  
2 securing a die to an interposer;  
3 securing a laminated conductor to the interposer to supply current to the die  
4 and mechanically support the interposer.
- 1 2. The method recited in claim 1, wherein securing a laminated conductor to  
2 the interposer includes securing a positive portion of the laminated conductor to a  
3 positive section of the interposer and securing a negative portion of the laminated  
4 conductor to a negative section of the interposer.
- 1 3. The method recited in claim 1, wherein securing the laminated conductor to  
2 the interposer includes securing the laminated conductor to the interposer on a side  
3 of the interposer that includes the die.
- 1 4. The method recited in claim 3, wherein securing the laminated conductor to  
2 the interposer includes securing the laminated conductor adjacent to the die.
- 1 5. The method recited in claim 1, wherein securing the laminated conductor to  
2 the interposer includes soldering the laminated conductor to a surface on the  
3 interposer using reflowable solder balls to establish an electrical connection.
- 1 6. The method recited in claim 5, wherein soldering the laminated conductor to  
2 the surface on the interposer includes underfilling areas between the laminated  
3 conductor and the interposer with an epoxy.

1 7. An electronic package comprising:  
2 an interposer;  
3 a die secured to the interposer; and  
4 a laminated conductor secured to the interposer to mechanically support the  
5 interposer and supply current to the die.

1 8. The electronic package of claim 7, wherein the interposer is a composite  
2 metal and organic material.

1 9. The electronic package of claim 7, wherein the interposer includes an upper  
2 surface and a lower surface and the die and the laminated conductor are secured to  
3 the upper surface of the interposer with the laminated conductor adjacent to the die.

1 10. The electronic package of claim 7, further comprising an electronic  
2 component secured to the lower surface of the die, the interposer being thin enough  
3 to reduce the inductive loop between the electronic component and the die.

1 11. The electronic package of claim 7, wherein the laminated conductor includes  
2 a positive portion that is connected to a positive section of the interposer and a  
3 negative portion that is connected to a negative section of the interposer.

1 12. The electronic package of claim 7, wherein the laminated conductor includes  
2 a pair of conducting sheets separated by a dielectric layer.

1 13. The electronic package of claim 12, wherein one of the sheets includes an  
2 opening and the other sheet includes a projection that extends into the opening.

- 1 14. The electronic package of claim 13, wherein the sheet with the openings  
2 includes an exposed surface and the projection includes a tip that is substantially  
3 aligned with the exposed surface.
- 1 15. The electronic package of claim 14, wherein the exposed surface and the tip  
2 of the projection are engaged with the interposer.
- 1 16. The electronic package of claim 7, wherein an end of the laminated  
2 conductor is folded over such that each of the sheets engages the interposer.
- 1 17. The electronic package of claim 7, wherein the interposer has a thickness  
2 that is less than 1 mm.
- 1 18. A computer system comprising:  
2 a bus;  
3 a memory coupled to the bus;  
4 a processor; and  
5 a package including an interposer and a laminated conductor secured to the  
6 interposer, the processor being secured to the interposer such that the laminated  
7 conductor electrically connects the processor to the bus and mechanically supports  
8 the interposer during operation of the computer system.
- 1 19. The computer system of claim 18, wherein the interposer has a thickness less  
2 than 1 mm.
- 1 20. The computer system of claim 18, wherein the laminated conductor and the  
2 processor are secured to a common side of the interposer.